



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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NI/CU POLYESTER CONDUCTIVE FABRIC TAPE

Laird's Conductive Fabric Tape 85785 is composed of metallized (nickel/copper) polyester based fabric and conductive pressure sensitive adhesive (PSA). The fabric layer offers excellent performance for EMI/RFI shielding and electrical grounding, while the adhesive layer makes it convenient to apply on most metal or plastic surfaces. This relatively stiff fabric tape is ideal for die cut and hole punched applications.

FEATURES

- RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Low surface resistivity of $< 0.04 \Omega/\square$ provides excellent conductivity
- Shielding effectiveness of >75 dB across a wide spectrum of frequencies

MARKETS

- Cabinet applications
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Laptop computers

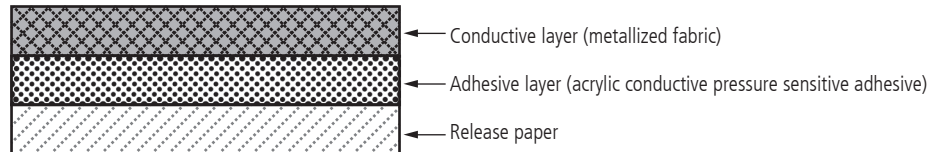


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Item	Unit	Value	Test Method
Thickness	mm	0.12 ± 0.02	-
Peel Adhesion	Kgf / 25 mm	>1.1	PSTC 101*
Shear Adhesion			
at R.T.	Hrs	>72	PSTC 107#
at 80°C	Hrs	>5	PSTC 107#
Tensile Strength	Kgf / 25 mm	>12	
Operation Temperature	°C	0-80	
Surface Resistivity (Fabric Side)	Ω/□	<0.04	ASTM F390
Z-axial Resistance	Ω	<0.04	
Shielding Effectiveness*			ASTM D4935
at 100 MHz	dB	75	
at 1GHz	dB	80	
Package Dimensions	M	W: 5 mm to 1000 mm L: Standard Length of 20 M	
Shelf Life (Under 23°C/65% R.H.)		One Year	

*:Test Method A, dwell time 30 min. #:Contact area 25 mm by 25 mm +:Typical value

COMPOSITION OF PRODUCT



APPLICATION TECHNIQUES

1. Bond strength is dependent upon the amount of adhesive-to-surface contact developed. Firm application pressure develops better adhesive contact and improves bond strength.
2. To obtain optimum adhesion, the bonding surfaces must be clean, dry and well unified.
3. The temperature of tape application is recommended 21°C to 38°C.
4. Not designed for cable wrapping or applications requiring high shear adhesion. Please contact your Laird Sales representative for a more suitable product.

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